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United States Patent [19]

Fan et al.

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[54] **WAFER POD**

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[73] Assignee: **Industrial Technology Research Institute**, Hsinchu, Taiwan

[**] Term: **14 Years**

[21] Appl. No.: **29/077,908**

[22] Filed: **Aug. 12, 1997**

[51] **LOC (6) Cl.** **03-01**

[52] **U.S. Cl.** **D3/273**; D3/269

[58] **Field of Search** D3/273, 269, 302; D9/420, 423, 424; 206/444, 445, 454, 455, 503, 508

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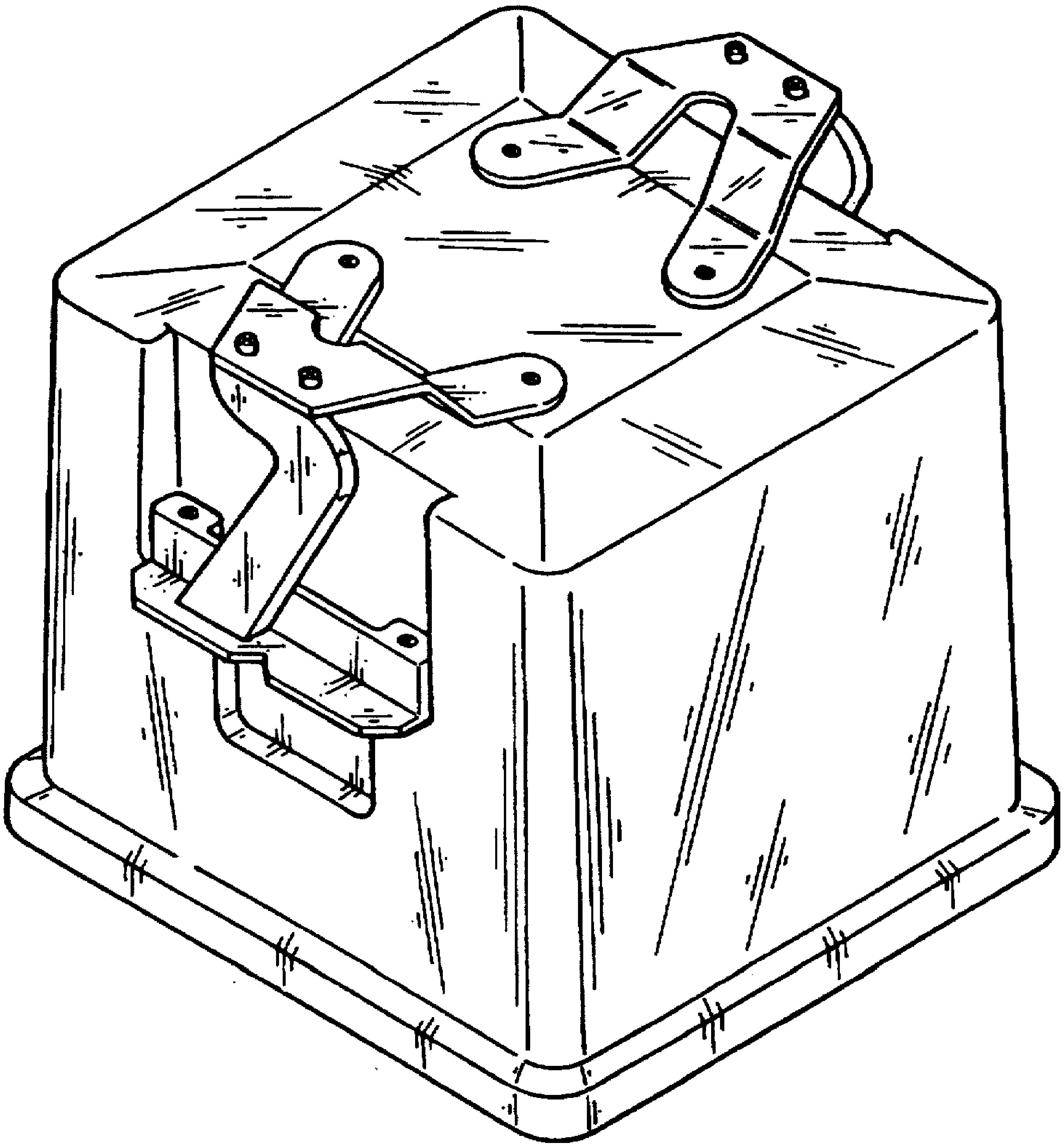
[57] **CLAIM**

The ornamental design for a wafer pod, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a wafer pod showing the preferred embodiment of my new design;
FIG. 2 is a front elevational view of the wafer pod;
FIG. 3 is a rear elevational view of the wafer pod;
FIG. 4 is a left elevational side view of the wafer pod;
FIG. 5 is a right elevational side view of the wafer pod;
FIG. 6 is a top plan view of the wafer pod; and,
FIG. 7 is a bottom plan view of the wafer pod.

1 Claim, 4 Drawing Sheets



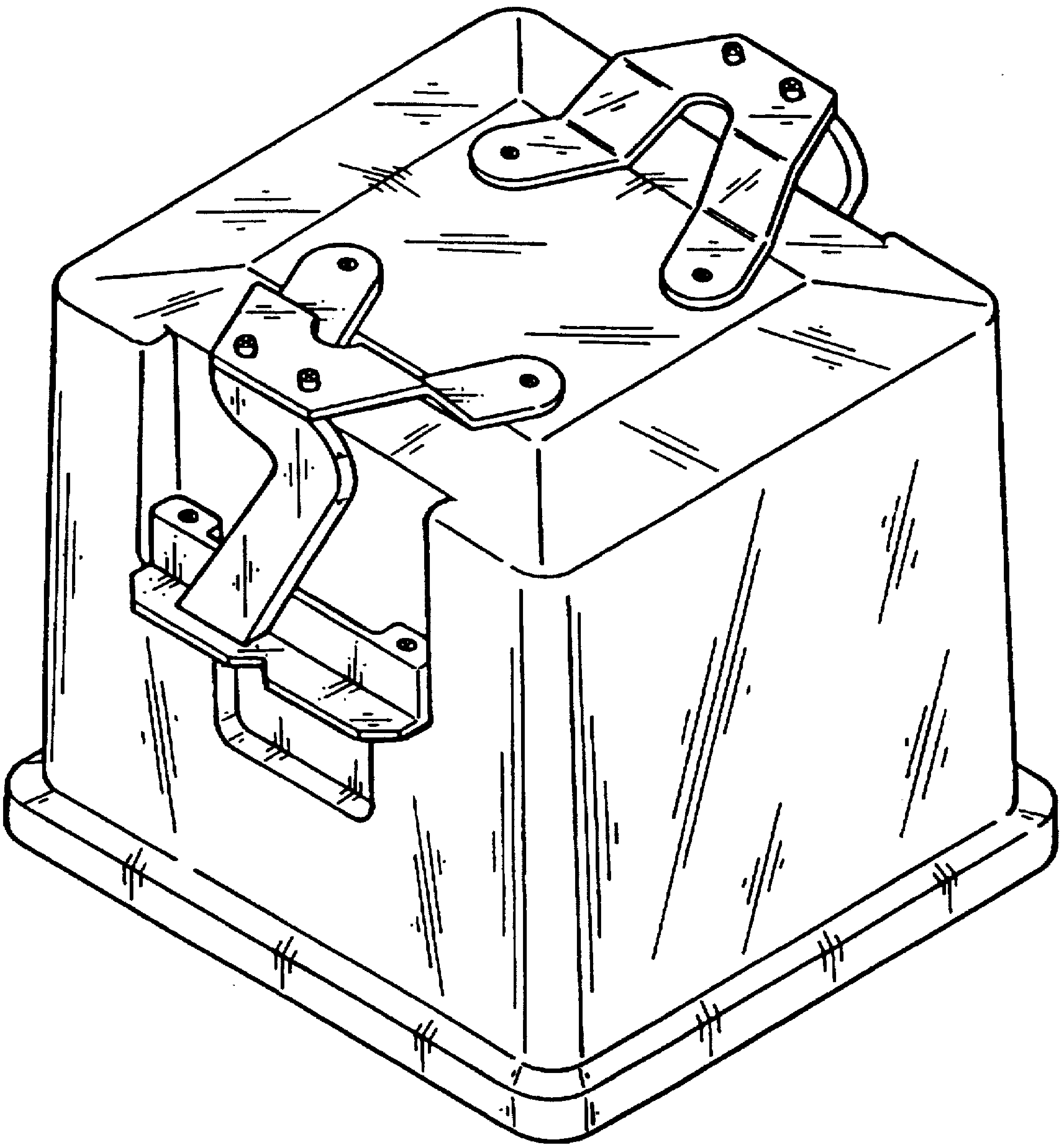


Fig . 1

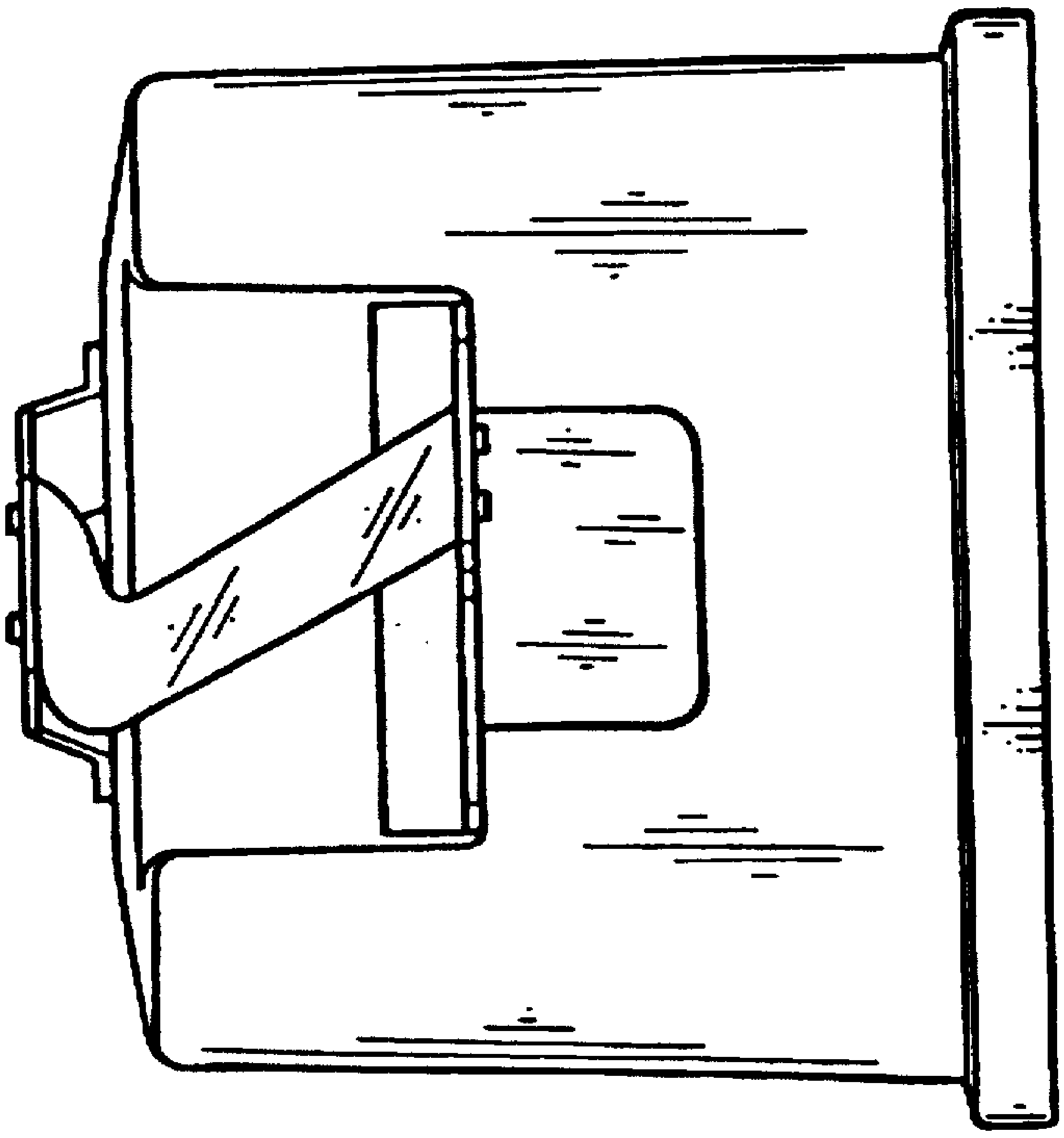


Fig . 3

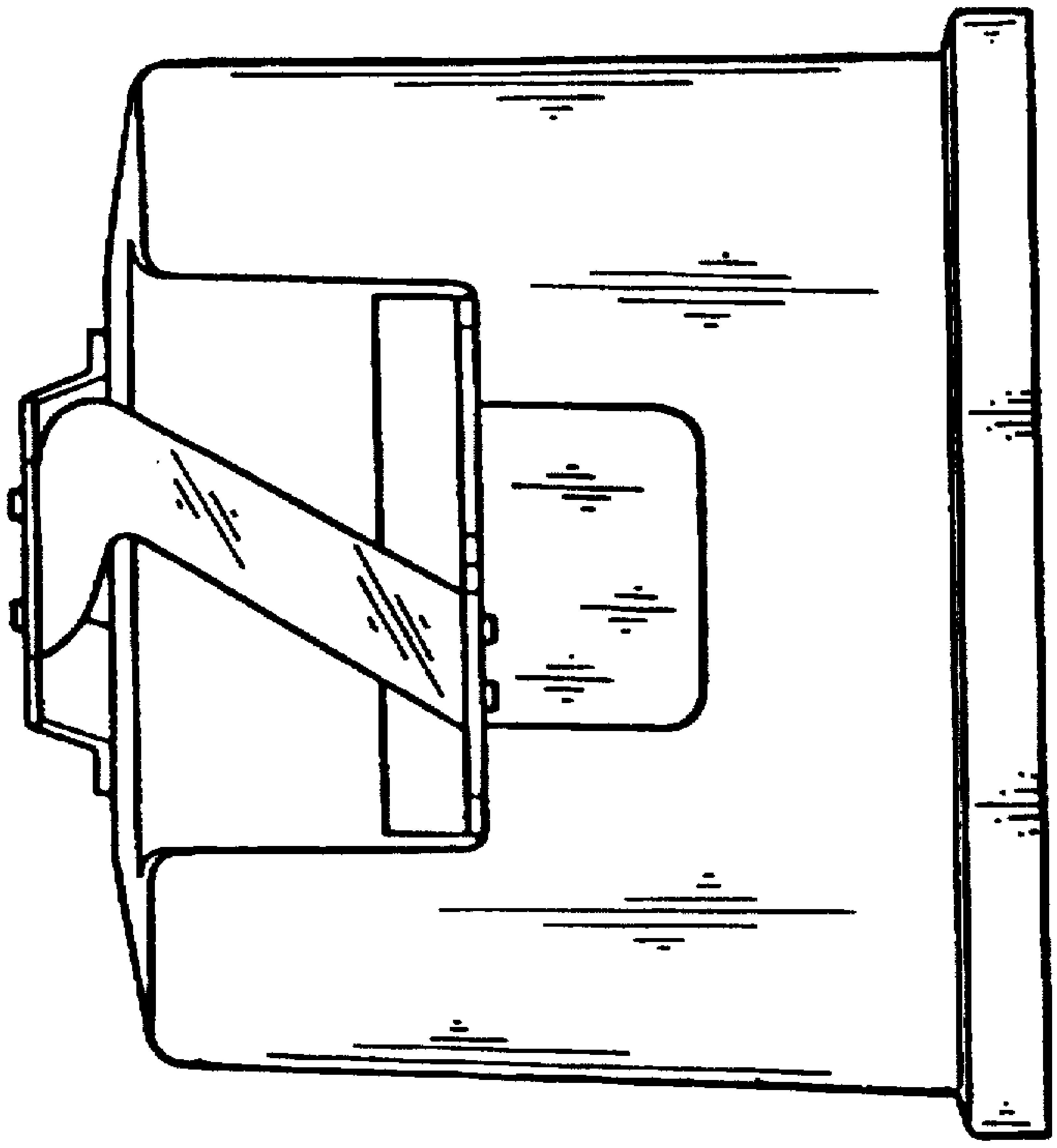


Fig . 2

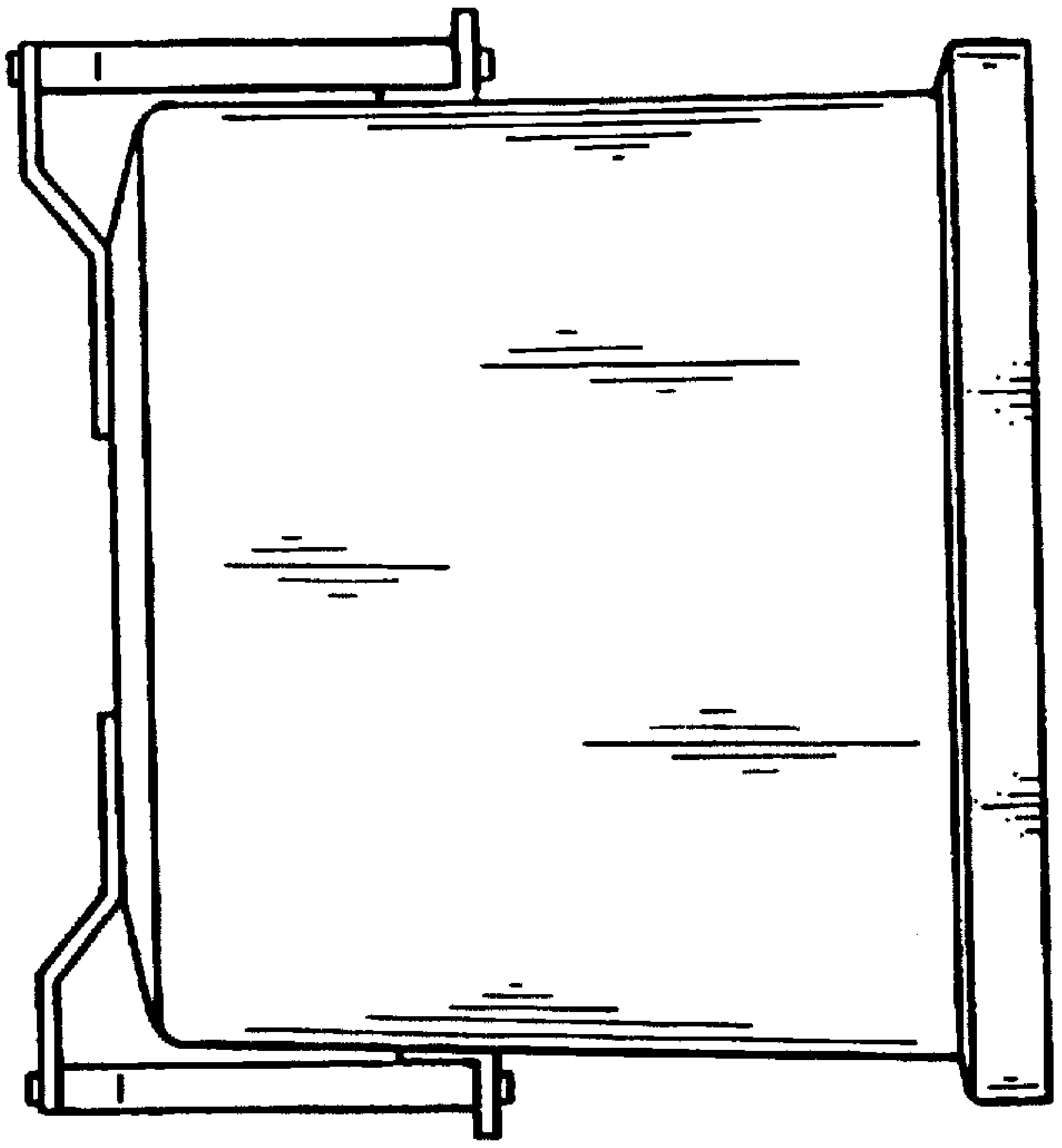


Fig. 5

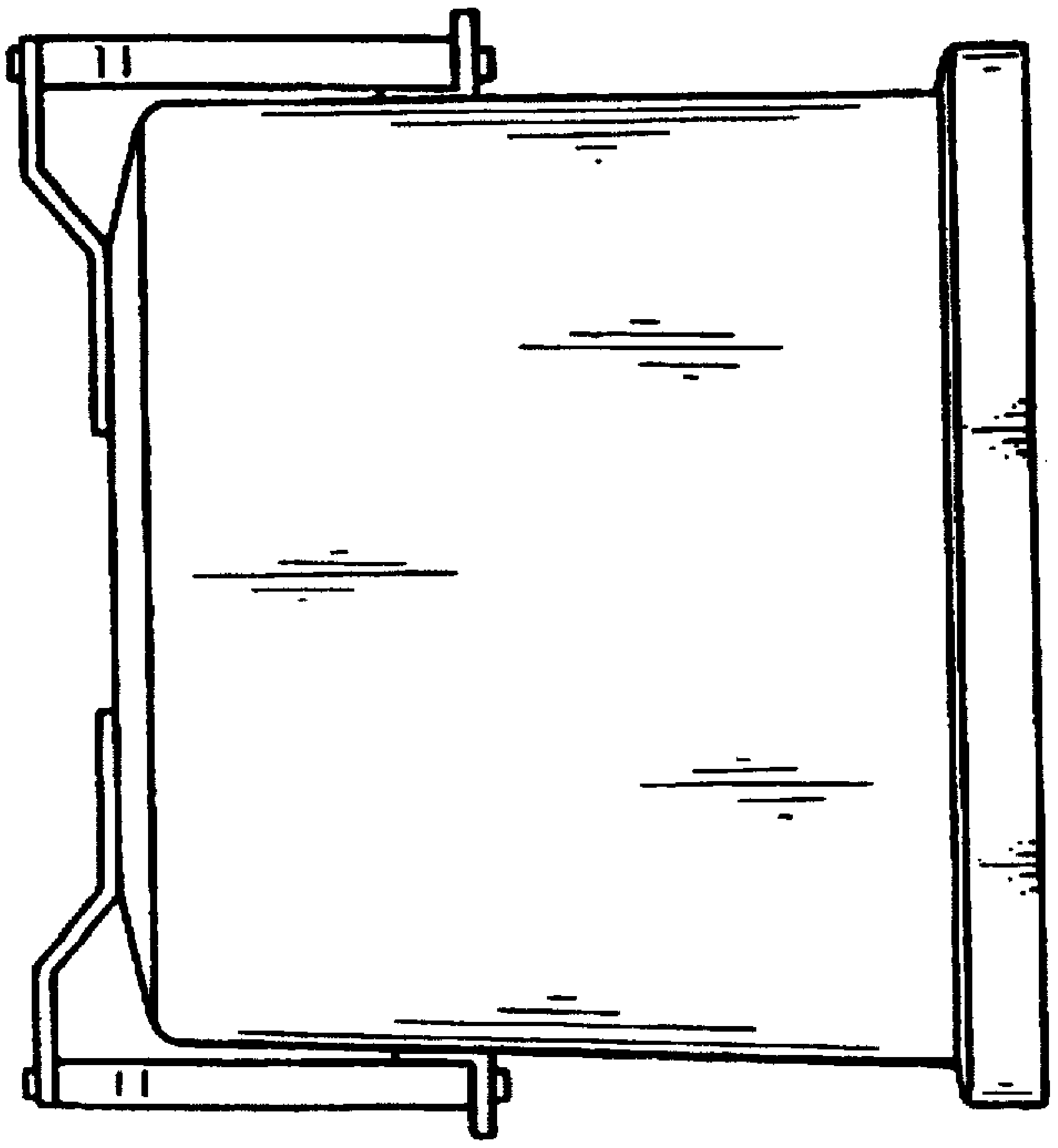


Fig. 4

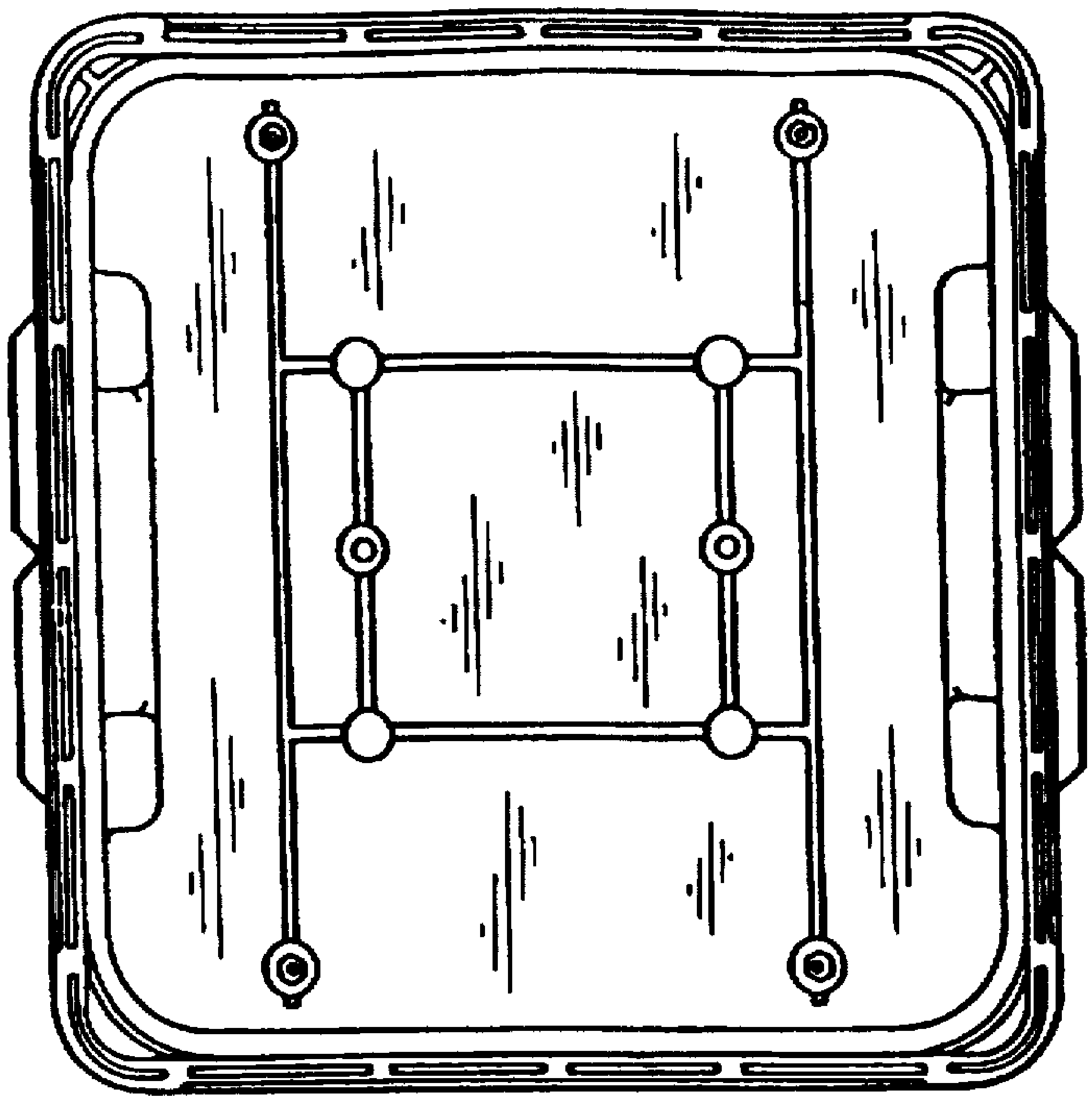


Fig. 7

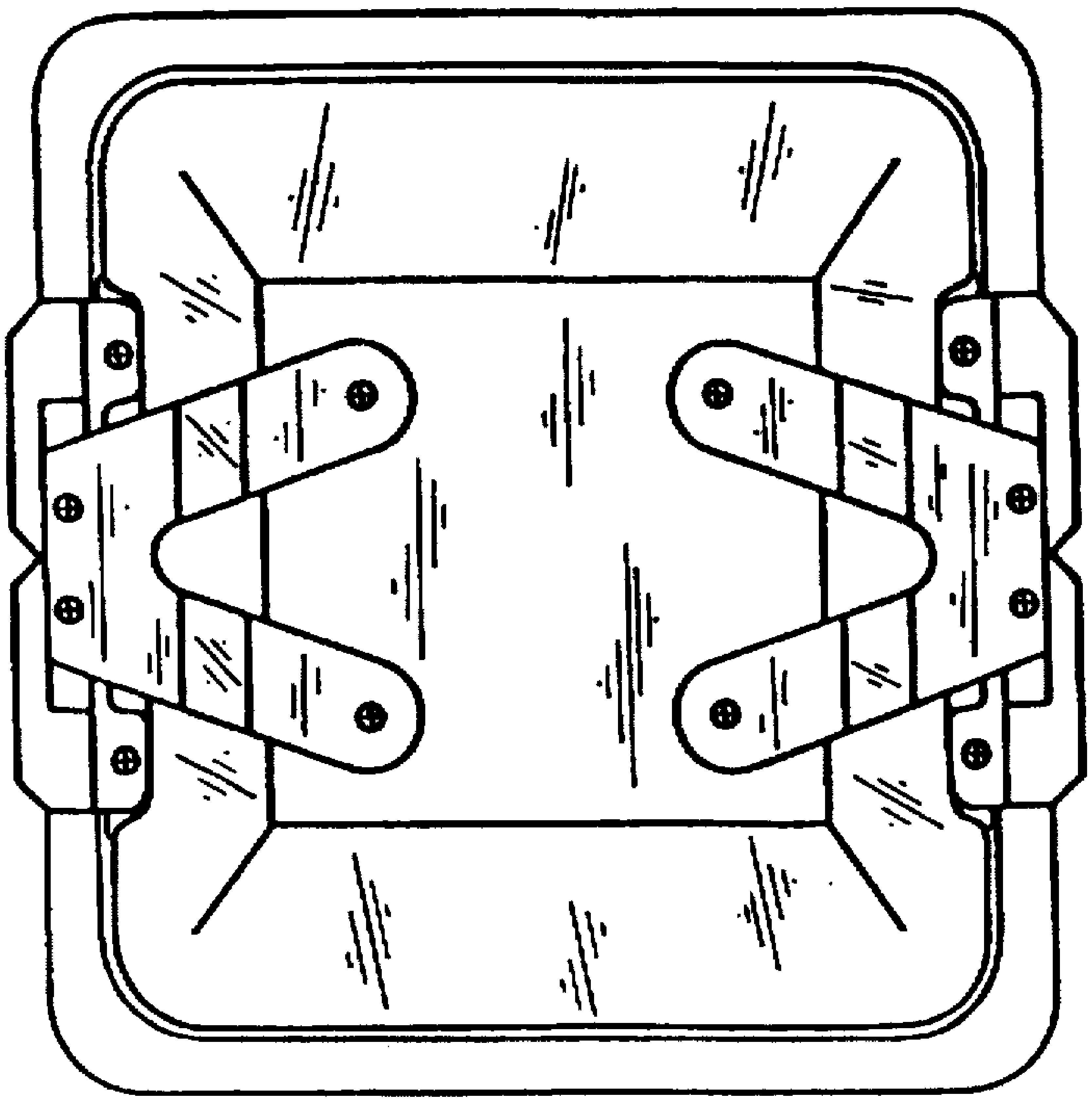


Fig. 6